IPC ASSOCIATION CONNECTINE ELECTRONICS INDUSTRIE	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				under both le	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with low level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.										
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Typ http://www.ipc.org/IPC-175x Form Typ Distribute				* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Mater					ials and Mfg Information					
Supplier Inforn	nation															
Company name*			Company un	Company unique ID			Unique ID Authority					Response Date*				
nsemi												2024-05-11				
Contact Name		Title - Contact			F	Phone - Contact*					Email - Contact*					
Product-Env-Stewa	ards	Product Enviro Compliance]	NA				Product-Env-Stewards@onsemi.com						
uthorized Represe	entative*	Title - Representative			F	Phone - Representative*				Email - Representative*						
Product-Env-Stewards			Product Enviro Compliance]	NA				Product-Env-Stewards@onsemi.com					
Requesto	ter Item Number Mfr Item		m Number Mfr Item Name				Effective Date Version Manu		Manufacturing Site		V	/eight*	*	UOM	Unit Type	
		NCP718BSN330T1G 300 mA 1 TSOT23-		300 mA Low Iq, TSOT23-5; 3V3	0 mA Low Iq, Wide Input Voltage LDO - OT23-5; 3V3 HZ		2024-05-11			ТНВ		1	12.52		mg	Each
Ianufacturing	Process Information	n														
Terminal	Plating / Grid Array Material		Terminal Base Alloy J		J-STD-020 MSL Rating		Peak Process Body Tempera		ody Temperatu	ture Max Time at Peak 7		Temperatu	mperature Number of Reflow Cycles		les	
Precious metal (e.g. Ag,Au, NiPdAu) (no Sn)		Au) (no	CU Alloy 1		1		260		C	30 seco		secono	s 3			
Comments																
vel 1 - maximum t	time at peak temperature	during so	ldering is 10-3	0 seconds												
or more informati	on regarding material co	mposition	please refer to	page 3												

RoHS Material Composition Declaration			Declaration Type *	Detail	ed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
cadmium, hexavalentchromium, polybromin contains a RoHS restricted substance inexce encompass all such components. Supplier cet as of the date that Supplier completes this Company acknowledges that Supplier may hindependently verified information provided certification in this paragraph. If the Compan	nated biphenyls and/or polybrominated diphess of an applicable quantity limit, please indriffes that it gathered the information it provom. Supplier acknowledges that Company wave relied on informationprovided by others of the supplier agrees that, at a minimusy and the Supplier enter into a written agree yesource of the Supplier's liability and the C	enyl ethers (each a "RoHS restricted substan licate below which, if any, RoHS exemption vides in this form using appropriate methods vill rely on this certification in determining the s in completing this form, and that Supplier um, itssuppliers have provided certifications ement with respect to the identified part, the tompany's remedies for issues that arise rega	s of the European Union member states) of the ce") in excess of the applicable quantity limit is you believe may apply. If the part is an assemb to ensure its accuracy and that such informatio e compliance of its products with European Ur may not have independently verified such infor regarding their contributions to the part, and the erms and conditions of that agreement, including information the Supplier provides in this	dentified above. If a ally with lower level in is true and correct tion member state la mation. However, in ose certifications are ag any warranty righ	homogeneous material within the part components, the declaration shall to the best of its knowledge and belief, was that implement the RoHS Directive. In situations where Supplier has not the at least as comprehensive as the lats and/or remedies provided as part of						
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted						
Exemption: If the declared item does not applicable exemptions.	contain RoHS restricted substances per t	he definition above except for defined Rol	IS exemptions, then select the corresponding	response in the R	oHS Declaration above and choose all						
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the						

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.3	mg	Supplier	Silicon (Si)	7440-21-3		0.3	mg
Die Attach Epoxy	0.1	mg	Supplier	Poly(oxypropylene)diamine	9046-10-0		0.003	mg
			Supplier	Silver (Ag)	7440-22-4		0.085	mg
			Supplier	Proprietary	Proprietary Data		0.005	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		0.007	mg
Lead Frame	6.43	mg	Supplier	Zinc (Zn)	7440-66-6		0.0077	mg
			Supplier	Iron (Fe)	7439-89-6		0.1511	mg
			Supplier	Copper (Cu)	7440-50-8		6.2692	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0019	mg
Mold Compound-Black	5.6	mg		Epoxy resin	proprietary data		0.28	mg
			Supplier	Phenolic Resin	Proprietary Data		0.112	mg
			Supplier	Ortho Cresol Novolac Resin	29690-82-2		0.14	mg
			Supplier	Carbon Black (C)	1333-86-4		0.028	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		5.04	mg
Plating	0.07	mg	Supplier	Palladium (Pd)	7440-05-3		0.0017	mg
			В	Nickel (Ni)	7440-02-0		0.0616	mg
			Supplier	Gold (Au)	7440-57-5		0.0067	mg
Wire Bond - Cu	0.02	mg	Supplier	Palladium (Pd)	7440-05-3		0.0004	mg
			Supplier	Gold (Au)	7440-57-5		0	mg
			Supplier	Copper (Cu)	7440-50-8		0.0196	mg